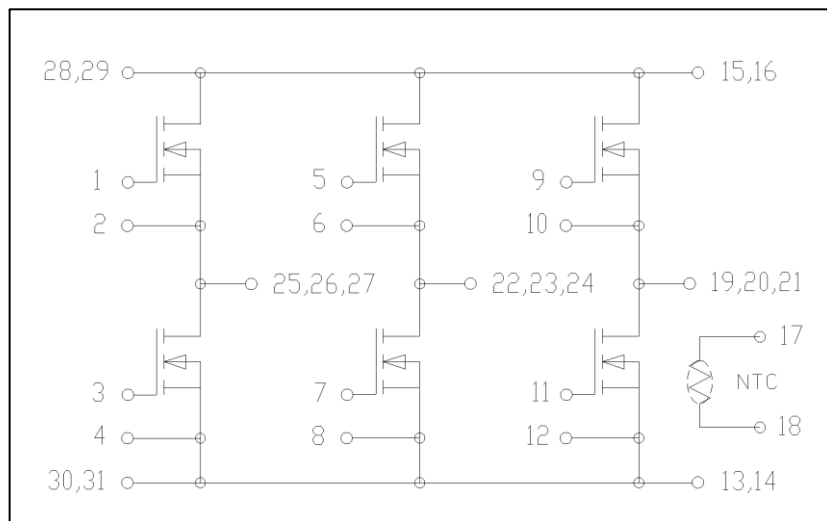


Six-Pack (Three Phase) SiC MOSFET Module
100 Amperes/1200 Volts



Description:

Powerex Silicon Carbide MOSFET Modules are designed for use in high frequency applications. Each module consists of six MOSFET Silicon Carbide Transistors. All Components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- Junction Temperature: 175°C
- Industry Leading $R_{ds(on)}$
- High Speed Switching
- Low Switching Losses
- Low Capacitance
- Low Drive Requirement
- High Power Density
- Isolated Baseplate
- Aluminum Nitride Isolation
- Wolfspeed® 3rd Generation Chips

Applications:

- Energy Saving Power Systems
- High Frequency Type Power Systems
- High Temperature Power Systems

Information presented is based upon manufacturers testing and projected capabilities. This information is subject to change without notice. The manufacturer makes no claim as to the suitability of use, reliability, capability, or future availability of this product.



Absolute Maximum Ratings, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	QJE1210SB1	Units
Drain-Source Voltage (G-S Short)	V_{DSS}	1200	Volts
Gate-Source Voltage	V_{GSS}	-4 / +15	Volts
Drain Current (Continuous) at $T_C=85^\circ\text{C}$	I_D	100	Amperes
Drain Current (Pulsed)* ¹	$I_{D(pulse)}$	200	Amperes
Maximum Power Dissipation ($T_C=25^\circ\text{C}$, $T_J < 175^\circ\text{C}$)	P_D	250	Watts
Junction Temperature	T_J	-40 to 175	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 150	$^\circ\text{C}$
Mounting Torque, M5 Mounting Screws	—	5	Nm
Module Weight (Typical)	—	180	Grams
Isolation Voltage	V_{ISO}	3000	Volts

*¹ Pulse width and repetition rate should be such that device junction temperature (T_J) does not exceed $T_{J(MAX)}$ rating.

DC Characteristics, $T_J=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain Source Leakage Current	I_{DSS}	$V_{DS}=1200\text{V}$, $V_{GS}=0\text{V}$ $T_J=175^\circ\text{C}$			0.5	mA
					TBD	mA
Gate Source Leakage Current	I_{GSS}	$V_{DS}=0\text{V}$, $V_{GS}=15\text{V}$			1000	nA
Recommended Gate Source Voltage	V_{GS}			-4/15V		Volts
Maximum Gate Source Voltage	$V_{GS(max)}$	$V_{DS}=0\text{V}$			-8/19V	
Gate Source Threshold Voltage	V_{th}	$V_{GS}=V_{DS}$, $I_{DS}=26.5\text{mA}$	1.8	2.5	3.6	Volts
Drain Source On-Resistance	$R_{DS(on)}$	$V_{GS}=15\text{V}$, $I_{SD}=180\text{A}$ $T_J=175^\circ\text{C}$	10	13	18	mΩ
				21		mΩ
Internal Gate Source Series Resistance Per MOSFET	$R_{gate(esr)}$	$V_{GS}=0\text{V}$, $f=1\text{MHz}$, Drain Floating		6.7		Ω

Dynamic Characteristics, T_J=25°C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance	C _{ISS}			7.6		nF
Output Capacitance	C _{OSS}	V _{GS} =0V, V _{DS} =1000V, f=1MHz		284		pF
Reverse Transfer Capacitance	C _{RSS}			18		pF
Turn-On Delay Time	t _{D(on)}			TBD		nS
Rise Time	t _R	V _{DD} =120V, V _{GS} = -4 to 15V,		TBD		nS
Turn-Off Delay Time	t _{D(off)}	I _D =100A, R _{G(max)} =0Ω		TBD		nS
Fall Time	t _F			TBD		nS
Turn-On Energy	E _{on}	V _{DD} =600V, V _{GS} =-4 to 15V,		2.6		mJ
Turn-Off Energy	E _{off}	I _D =100A, R _G =0Ω		2.4		mJ
Recovery Energy	E _{rr}	T _J =175°C		0.38		mJ
Total Gate Charge	Q _G	V _{DD} =800V, V _{GS} =-4 to 15V I _D =100A, T _J =25°C		260		nC

Body Diode, T_J=25°C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Reverse Recovery Current, Peak	I _{RR}	V _{GS} =-4V, I _D =100A		65		Amps
Reverse Recovery Charge	Q _{RR}	V _R =800V, di/dt=3000A/μs		1.8		μC
Diode Forward Voltage	V _{SD}	V _{GS} =-4V I _{SD} =32.1A		4.6		V
		T _J =175°C		4.2		V

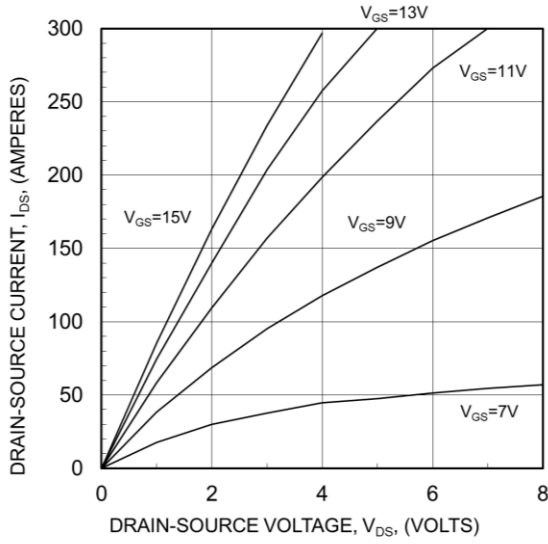
Thermal Resistance Characteristics

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	R _{th(j-c)}	Per MOSFET			0.045	°C/W
Contact Thermal Resistance	R _{th(c-s)}	Per Module, Thermal Grease Applied		0.07		°C/W

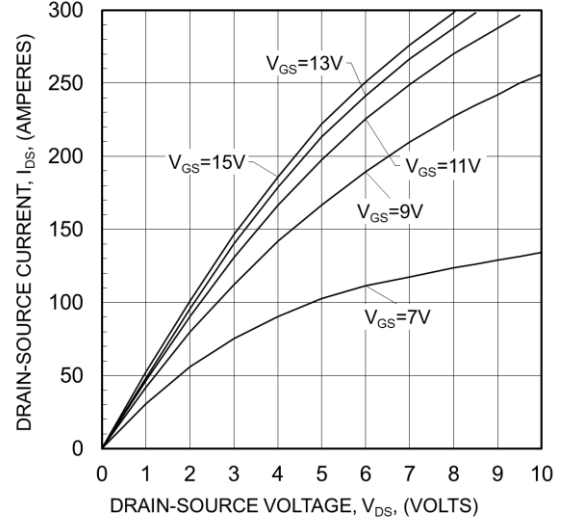
NTC Thermistor Part

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Zero Power Resistance	R ₂₅	T _C =25°C	4.85	5.00	5.15	kΩ
Deviation of Resistance	ΔR/R	T _C =100°C, R ₁₀₀ =493Ω	-7.3	—	+7.8	%
B constant	B _(25/50)	B _(25/50) =ln(R ₂₅ /R ₅₀) / (1/T ₂₅ - 1/T ₅₀) ⁻¹	—	3375	—	K
Power Dissipation	P ₂₅	T _C =25°C	—	—	10	mW

OUTPUT CHARACTERISTICS
 $T_j = 25^\circ\text{C}$, $t_p < 200 \mu\text{s}$

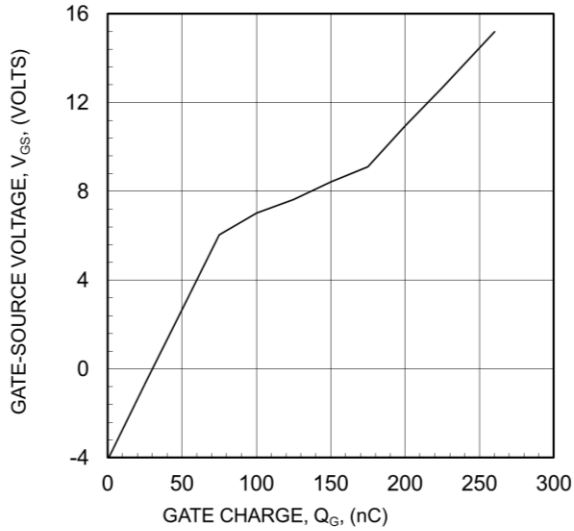


OUTPUT CHARACTERISTICS
 $T_j = 175^\circ\text{C}$, $t_p < 200 \mu\text{s}$



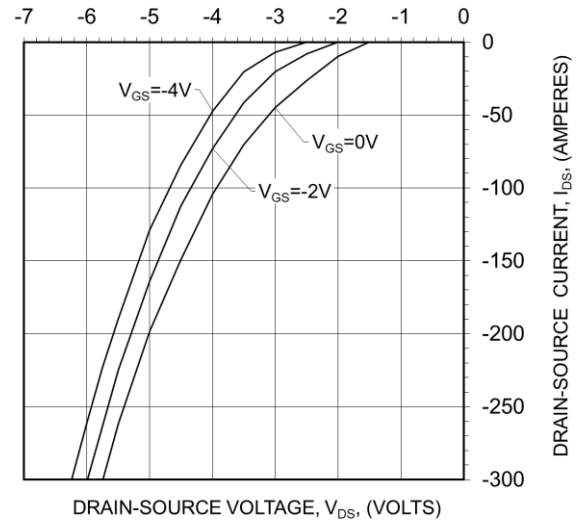
GATE CHARGE

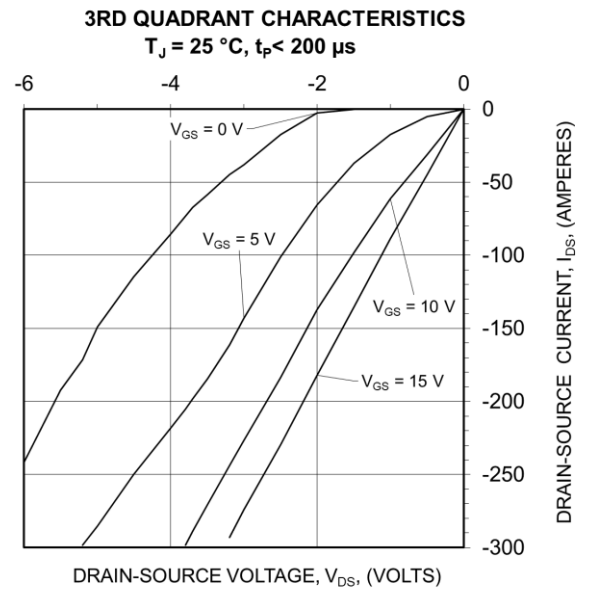
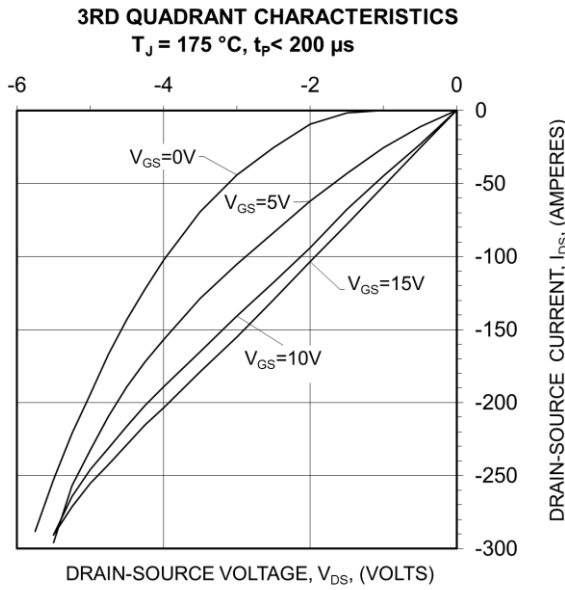
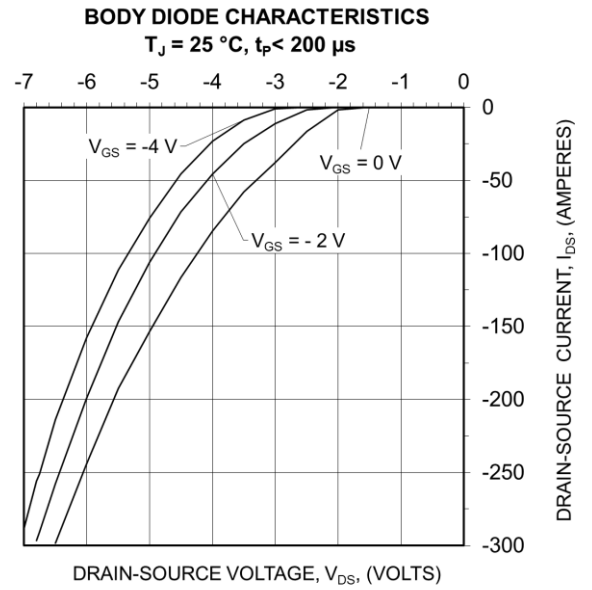
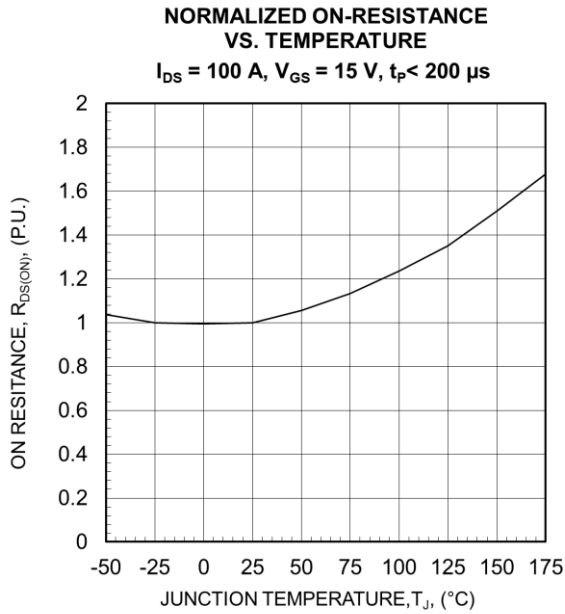
$I_{DS} = 100 \text{ A}$, $I_{GS} = 50 \text{ mA}$, $V_{DS} = 800 \text{ V}$, $T_j = 25^\circ\text{C}$



BODY DIODE CHARACTERISTICS

$T_j = 175^\circ\text{C}$, $t_p < 200 \mu\text{s}$





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